

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-6 are currently pending. Claims 1 and 2 have been amended by the present amendment. The amendments to the claims are supported by the originally filed specification and do not add new matter.<sup>1</sup>

In the outstanding Office Action, Claims 1-6 were rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,370,768 to Itabashi (hereinafter, “Itabashi”) and U.S. Patent No. 6,319,831 to Tsai et al. (hereinafter, “Tsai”).

Applicants wish to thank the Examiner for the interview granted to Applicants’ representatives on April 5, 2010, at which time the outstanding rejections of the claims in view of Tsai, and proposed amendments to the claims, were discussed, as substantially summarized hereinafter. At the end of the discussion, the Examiner indicated that further consideration and/or review would be given upon filing of an official response.

Applicants’ Claim 1 is directed to a method of manufacturing an electronic part comprising in part:

growing metal plating layers, as conductor portions from each of the bottoms of said opening holes, from said lower conductor layer as an electrode; and

growing the metal plating layers on upper surfaces of said conductor film and said conductor portions with said conductor film and said conductor portions as electrodes after said conductor portions are formed in the respective plurality of opening holes by growing said metal plating layers so as to contact said metal plating layers with said conductor film, and to *increase area for growing said metal plating layers and reduce current density per unit in said metal plating layers, so as to lower growing speed of said metal plating layers*, to thereby form said conductor portions in said opening holes, and forming a thickness enough to form an upper conductor layer, wherein

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<sup>1</sup> See, e.g., page 6, lines 2-8, in Applicants’ specification.

the metal plating layers are grown from each of the bottoms of said opening holes, and on the upper surfaces of said conductor film and said conduction portions, ***without electroless plating being carried out.*** [Emphasis Added]

Claim 1 clarifies that the metal plating layers are grown from the bottoms of the opening holes, and on upper surfaces of the conductor film and the conductor portions, without electroless plating being carried out. Further, Claim 1 clarifies that the growing of the metal plating layers on upper surfaces of the conductor film and the conductor portions increases the area for growing the metal plating layers and reduce current density per unit in the metal plating layers, so as to lower growing speed of the metal plating layers.

As discussed during the interview, Applicants respectfully submit that the art of record does ***not*** disclose or suggest growing the metal plating layers without electroless plating being carried out to increase the area for growing the metal plating layers and reduce current density per unit in the metal plating layers, so as to lower growing speed of the metal plating layers.

The above discussion regarding independent Claim 1 also applies to independent Claim 7, which recites analogous features in a claim of a different scope.

Accordingly, Applicants respectfully request that the 35 U.S.C. § 103(a) rejections of independent Claims 1 and 2 be withdrawn.

In addition, for the reasons discussed above regarding independent Claims 1 and 2, it is respectfully requested that the 35 U.S.C. § 103(a) rejections of dependent Claims 3-6, which directly or indirectly depend from independent Claims 1 or 2, also be withdrawn.

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Consequently, in view of the present amendment and in light of the above discussion, the outstanding grounds for rejection are believed to have been overcome. The application as amended herewith is believed to be in condition for formal allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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